



Laird™ Tflex™ HR600

Tflex™ HR600 is a cost-effective and compliant gap filler thermal interface material with excellent thermal performance and great handling for mass-production applications. The low modulus interface pad conforms to component topography, resulting in little stress on the components, mating chassis or parts. The softness relieves mechanical stress from high stack-up tolerance and absorbs shock, resulting in improved device reliability. Tflex HR600’s recovery properties for applications requiring material rework result in continued mechanical integrity even after device rework and re-assembly. Tflex HR600 is naturally tacky on both sides and requires no additional adhesive coating to inhibit thermal performance. The tack is designed to hold the pad in place during assembly and component transport.

TECHNICAL DATA SHEET | (EFFECTIVE 24FEB25)

Laird™ Tflex™ HR600

PHYSICAL PROPERTY	TEST METHOD	UNIT	VALUE
Construction & Composition		-	Ceramic filled silicone sheet
Color		-	Dark Grey
Thickness Range		mm in	0.25 - 5 0.01 - 0.2
Thickness Tolerance		%	10
Thermal Conductivity	D5470	w/mk	3.0
Density	Helium Pyncometer	g/cc	2.5
Outgassing TML	ASTM E595	%	0.19
Outgassing CVCM	ASTM E595	%	0.07
Temperature Range	Laird Test Method	°C	-45 to 200
Hardness Shore 00 (3 sec)	ASTM 2240	-	40
Rth @ 40 mils, 10 psi	ASTM D5470 (Modified)	°C-in²/w	0.35
Dielectric Constant @ 1 MHz	ASTM D150	-	19
UL Flammability Rating	UL 94	-	V-0
Volume Resistivity	ASTM D257	Ω-cm	1 × 10 ¹³